

C L A I M S

What is claimed is:

1. A test apparatus for providing contact with a plurality of electrically conductive members of an electronic component, said test apparatus comprising:
 - a compressible housing adapted for having an electronic component including a plurality of electrically conductive members compressibly positioned therein;
 - a base member including a plurality of compressible probes positioned therein; and
 - structures for bringing said compressible housing having said electronic component therein and said base member together such that selected ones of said compressible probes engage respective ones of said electrically conductive members of said electronic component.
2. The test apparatus of claim 1 wherein said compressible housing includes a base and a cover.
3. The test apparatus of claim 2 wherein said base defines an opening therein, said electronic component adapted for being positioned within said opening.
4. The test apparatus of claim 2 wherein said base includes a plurality of apertures therein, said selected ones of said compressible probes adapted for passing through respective ones of said apertures to engage said respective ones of said electrically conductive members.
5. The test apparatus of claim 2 further including a lock member movably positioned within said cover to lock said cover onto said base in a compressible manner.

6. The test apparatus of claim 5 wherein said lock member is a rotational screw adapted for being screwed into said base to provide said lock of said cover onto said base.
7. The test apparatus of claim 2 further including a compressible member adapted for being positioned between said base and cover, and between said cover and said electronic component when said electronic component is positioned within said compressible housing.
8. The test apparatus of claim 7 wherein said compressible member is a compliant pad.

9. The test apparatus of claim 2 wherein said base of said compressible housing is adapted for being positioned on said base member.
10. The test apparatus of claim 9 wherein said base member includes at least one upstanding alignment member and said base includes an opening therein, said upstanding alignment member adapted for passing through said opening in said base during said bringing of said compressible housing and said base member together such that said base will engage said alignment member in such a manner so as to prohibit excessive force application onto said electrically conductive members by said compressible probes.
11. The test apparatus of claim 10 wherein said upstanding alignment member includes an adjustable member adapted for adjusting the positional relationship between said compressible housing and said base member.
12. The test apparatus of claim 1 further including a conductive substrate having a plurality of conductive pads thereon, said base member adapted for being positioned on said conductive substrate such that said selected ones of said compressible probes electrically engage a respective one of said conductive pads.

13. The test apparatus of claim 12 wherein said conductive substrate comprises a printed circuit board.
14. The test apparatus of claim 1 wherein said structure for bringing said compressible housing and said base member together comprises a pneumatically-driven member.
15. The test apparatus of claim 14 wherein said pneumatic-driven member is a piston, said piston adapted for engaging said compressible housing.
16. A method of testing an electronic component having a plurality of electrically conductive members, said method comprising:
 - positioning an electronic component having a plurality of electrically conductive members within a compressible housing;
 - providing a base member including a plurality of compressible probes therein; and
 - bringing said compressible housing having said electronic component therein and said base member together such that selected ones of said compressible probes engage respective ones of said electrically conductive members of said electronic component.
17. The method of claim 16 wherein said compressible housing includes a base and cover and said positioning of said electronic component comprises positioning said component on said base and locking said cover onto said base to lock said electronic component in position.
18. The method of claim 17 further including positioning a compressible member substantially between said electronic component and said cover prior to said locking of said cover onto said base.

19. The method of claim 17 wherein said base is provided with a plurality of apertures therein, said bringing together of said compressible housing and said base member causing selected ones of said compressible probes to pass through respective ones of said apertures prior to engaging electrically conductive members.
20. The method of claim 16 wherein said compressible housing and said base member engage in such a manner so as to prohibit excessive force application onto said electrically conductive members by said compressible probes.